

## Electronic Patent Application Fee Transmittal

Application Number:	10720579			
Filing Date:	24-Nov-2003			
<b>Title of Invention:</b> Method for manufacturing very low roughness electrodeposited copper foil and electrodeposited copper foil manufactured thereby				
First Named Inventor/Applicant Name:	Sangyum Kim			
Filer:	Andrew W. Chu			
Attorney Docket Number:	1772-5			
Filed as Large Entity				
<b>Utility under 35 USC 111(a) Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
Petition-revive unintent. abandoned appl	1453	1	1620	1620
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1620</b>